

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

BC846ALT1 Series

BC846, BC847 and BC848 are Preferred Devices

General Purpose Transistors

NPN Silicon

Features

- Moisture Sensitivity Level: 1
- ESD Rating – Human Body Model: >4000 V
– Machine Model: >400 V
- Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage BC846 BC847, BC850 BC848, BC849	V_{CEO}	65 45 30	Vdc
Collector-Base Voltage BC846 BC847, BC850 BC848, BC849	V_{CBO}	80 50 30	Vdc
Emitter-Base Voltage BC846 BC847, BC850 BC848, BC849	V_{EBO}	6.0 6.0 5.0	Vdc
Collector Current – Continuous	I_C	100	mAdc

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

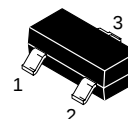
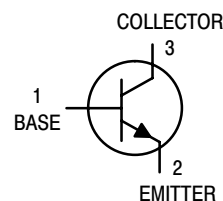
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	556	$^\circ\text{C/W}$
Total Device Dissipation Alumina Substrate (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	417	$^\circ\text{C/W}$
Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

- FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- Alumina = $0.4 \times 0.3 \times 0.024$ in 99.5% alumina.



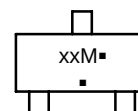
ON Semiconductor®

<http://onsemi.com>



SOT-23
CASE 318
STYLE 6

MARKING DIAGRAM



xx = Specific Device Code
M = Date Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

BC846ALT1 Series

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage ($I_C = 10\text{ mA}$)	BC846A,B BC847A,B,C, BC850B,C BC848A,B,C, BC849B,C $V_{(BR)CEO}$	65 45 30	– – –	– – –	V
Collector–Emitter Breakdown Voltage ($I_C = 10\text{ }\mu\text{A}$, $V_{EB} = 0$)	BC846A,B BC847A,B,C BC850B,C BC848A,B,C, BC849B,C $V_{(BR)CES}$	80 50 30	– – –	– – –	V
Collector–Base Breakdown Voltage ($I_C = 10\text{ }\mu\text{A}$)	BC846A,B BC847A,B,C, BC850B,C BC848A,B,C, BC849B,C $V_{(BR)CBO}$	80 50 30	– – –	– – –	V
Emitter–Base Breakdown Voltage ($I_E = 1.0\text{ }\mu\text{A}$)	BC846A,B BC847A,B,C, BC850B,C BC848A,B,C, BC849B,C $V_{(BR)EBO}$	6.0 6.0 5.0	– – –	– – –	V
Collector Cutoff Current ($V_{CB} = 30\text{ V}$) ($V_{CB} = 30\text{ V}$, $T_A = 150^\circ\text{C}$)	I_{CBO}	– –	– –	15 5.0	nA μA
ON CHARACTERISTICS					
DC Current Gain ($I_C = 10\text{ }\mu\text{A}$, $V_{CE} = 5.0\text{ V}$) ($I_C = 2.0\text{ mA}$, $V_{CE} = 5.0\text{ V}$)	BC846A, BC847A, BC848A BC846B, BC847B, BC848B BC847C, BC848C BC846A, BC847A, BC848A BC846B, BC847B, BC848B, BC849B, BC850B BC847C, BC848C, BC849C, BC850C h_{FE}	– – – 110 200 420	– 90 150 270 180 290 520	– – – 220 450 800	–
Collector–Emitter Saturation Voltage ($I_C = 10\text{ mA}$, $I_B = 0.5\text{ mA}$) ($I_C = 100\text{ mA}$, $I_B = 5.0\text{ mA}$)	$V_{CE(sat)}$	– –	– –	0.25 0.6	V
Base–Emitter Saturation Voltage ($I_C = 10\text{ mA}$, $I_B = 0.5\text{ mA}$) ($I_C = 100\text{ mA}$, $I_B = 5.0\text{ mA}$)	$V_{BE(sat)}$	– –	0.7 0.9	– –	V
Base–Emitter Voltage ($I_C = 2.0\text{ mA}$, $V_{CE} = 5.0\text{ V}$) ($I_C = 10\text{ mA}$, $V_{CE} = 5.0\text{ V}$)	$V_{BE(on)}$	580 –	660 –	700 770	mV
SMALL–SIGNAL CHARACTERISTICS					
Current–Gain – Bandwidth Product ($I_C = 10\text{ mA}$, $V_{CE} = 5.0\text{ Vdc}$, $f = 100\text{ MHz}$)	f_T	100	–	–	MHz
Output Capacitance ($V_{CB} = 10\text{ V}$, $f = 1.0\text{ MHz}$)	C_{obo}	–	–	4.5	pF
Noise Figure ($I_C = 0.2\text{ mA}$, $V_{CE} = 5.0\text{ Vdc}$, $R_S = 2.0\text{ k}\Omega$, $f = 1.0\text{ kHz}$, $BW = 200\text{ Hz}$)	BC846A,B, BC847A,B,C, BC848A,B,C BC849B,C, BC850B,C NF	– –	– –	10 4.0	dB

BC846ALT1 Series

BC847, BC848, BC849, BC850

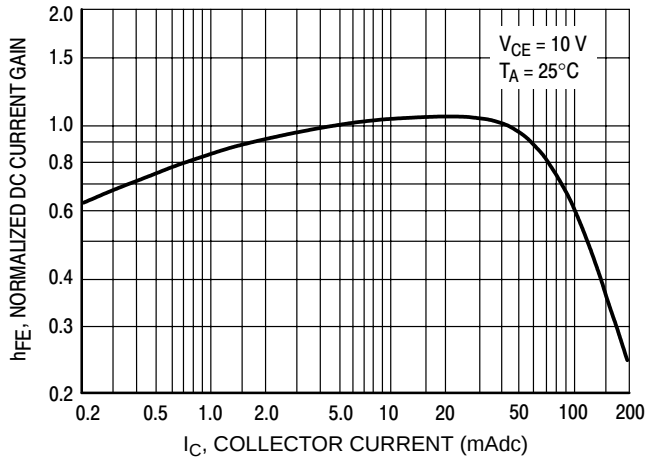


Figure 1. Normalized DC Current Gain

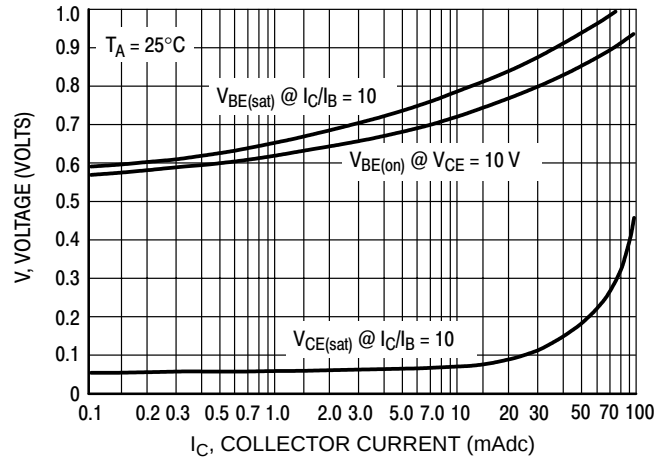


Figure 2. "Saturation" and "On" Voltages

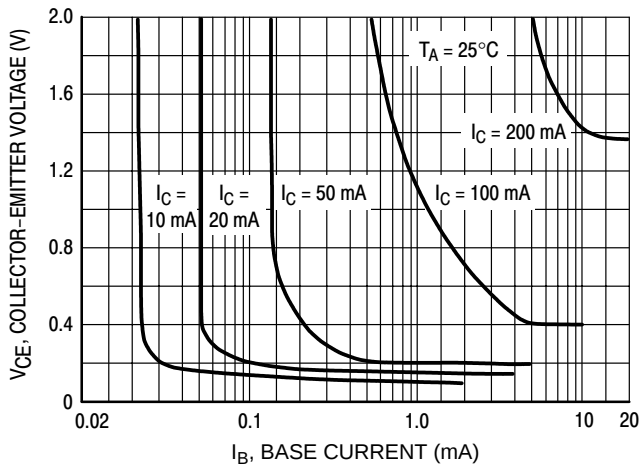


Figure 3. Collector Saturation Region

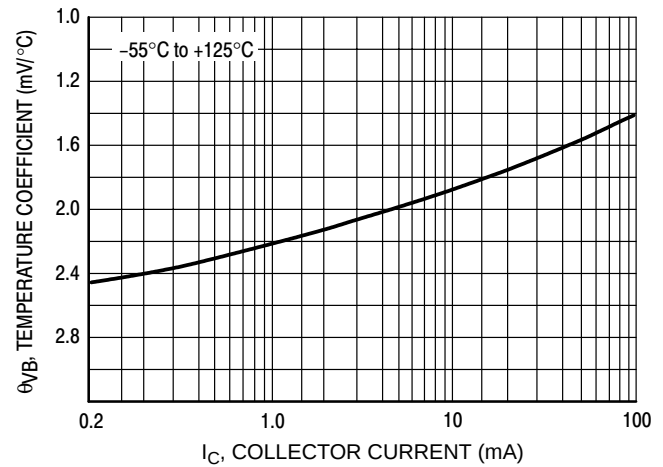


Figure 4. Base-Emitter Temperature Coefficient

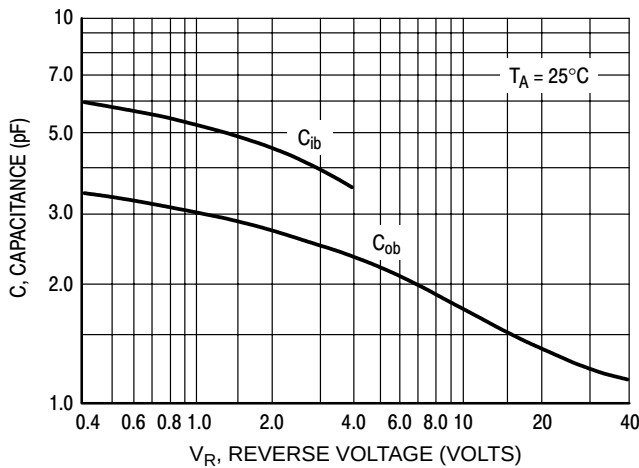


Figure 5. Capacitances

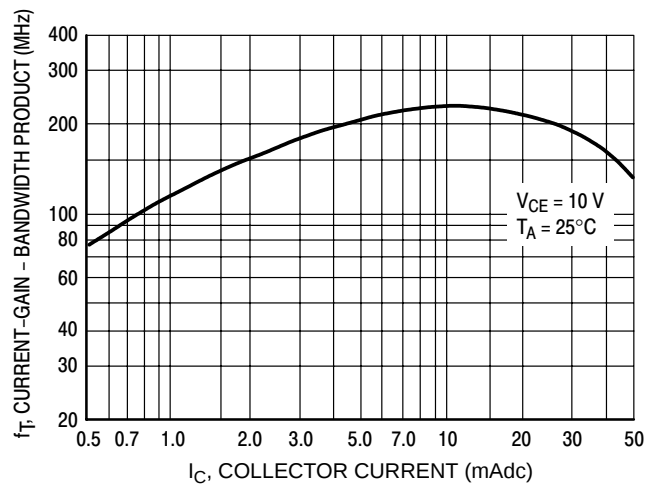


Figure 6. Current-Gain - Bandwidth Product

BC846ALT1 Series

BC846

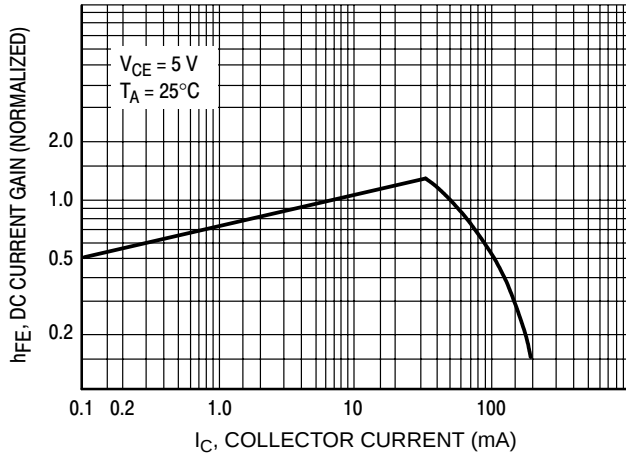


Figure 7. DC Current Gain

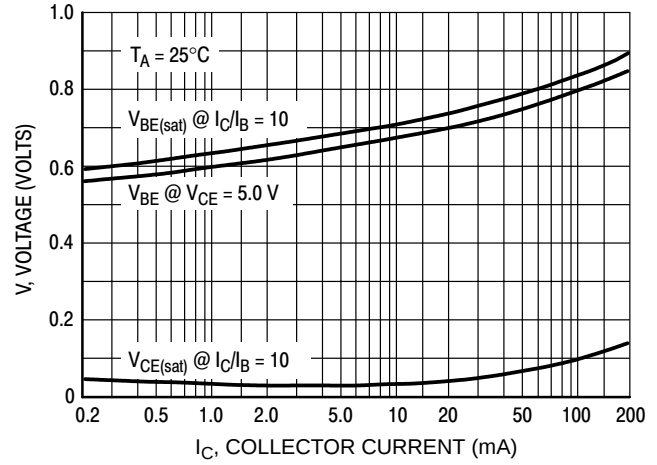


Figure 8. "On" Voltage

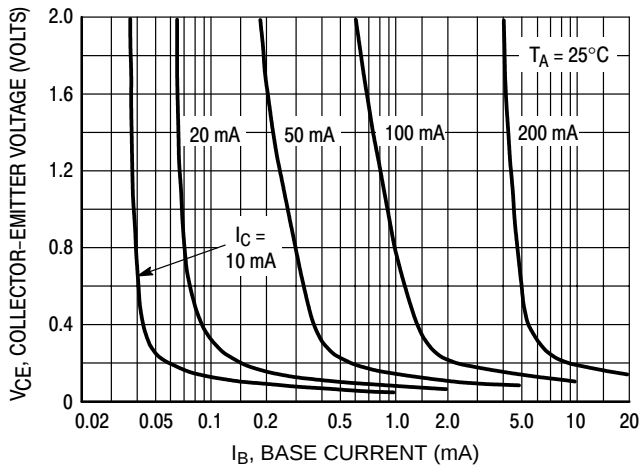


Figure 9. Collector Saturation Region

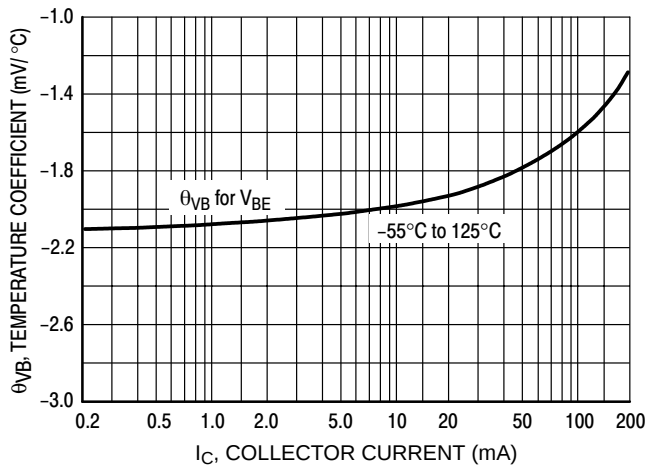


Figure 10. Base-Emitter Temperature Coefficient

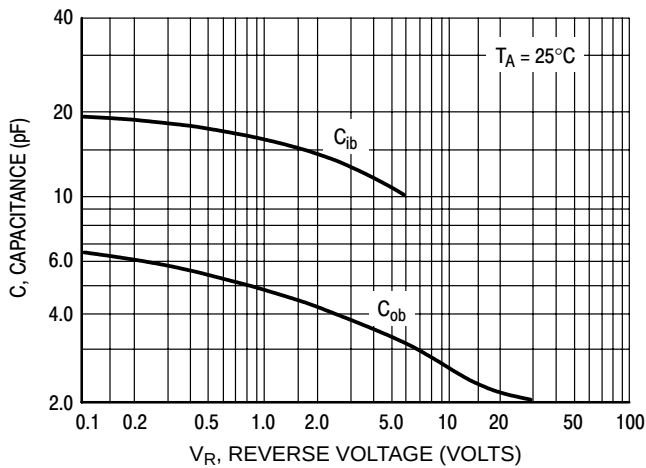


Figure 11. Capacitance

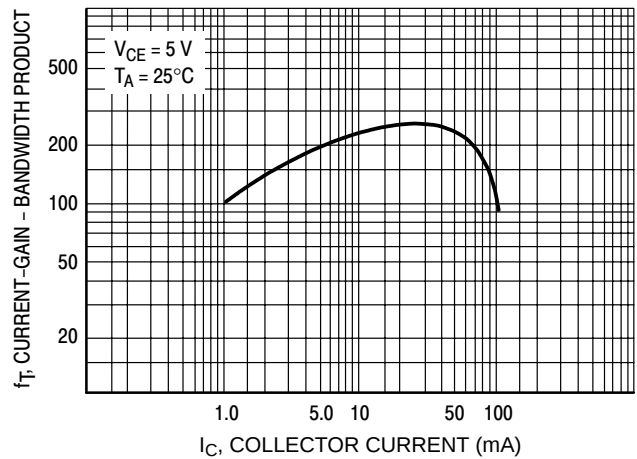


Figure 12. Current-Gain - Bandwidth Product

BC846ALT1 Series

ORDERING INFORMATION

Device	Marking	Package	Shipping†
BC846ALT1	1A	SOT-23	3,000 / Tape & Reel
BC846ALT1G		SOT-23 (Pb-Free)	
BC846ALT3		SOT-23	10,000 / Tape & Reel
BC846ALT3G		SOT-23 (Pb-Free)	
BC846BLT1	1B	SOT-23	3,000 / Tape & Reel
BC846BLT1G		SOT-23 (Pb-Free)	
BC846BLT3		SOT-23	10,000 / Tape & Reel
BC846BLT3G		SOT-23 (Pb-Free)	
BC847ALT1	1E	SOT-23	3,000 / Tape & Reel
BC847ALT1G		SOT-23 (Pb-Free)	
BC847ALT3		SOT-23	10,000 / Tape & Reel
BC847ALT3G		SOT-23 (Pb-Free)	
BC847BLT1	1F	SOT-23	3,000 / Tape & Reel
BC847BLT1G		SOT-23 (Pb-Free)	
BC847BLT3		SOT-23	10,000 / Tape & Reel
BC847BLT3G		SOT-23 (Pb-Free)	
BC847CLT1	1G	SOT-23	3,000 / Tape & Reel
BC847CLT1G		SOT-23 (Pb-Free)	
BC847CLT3		SOT-23	10,000 / Tape & Reel
BC847CLT3G		SOT-23 (Pb-Free)	
BC848ALT1	1J	SOT-23	3,000 / Tape & Reel
BC848ALT1G		SOT-23 (Pb-Free)	
BC848BLT1	1K	SOT-23	
BC848BLT1G		SOT-23 (Pb-Free)	10,000 / Tape & Reel
BC848BLT3		SOT-23	
BC848BLT3G		SOT-23 (Pb-Free)	
BC848CLT1	1L	SOT-23	3,000 / Tape & Reel
BC848CLT1G		SOT-23 (Pb-Free)	
BC848CLT3		SOT-23	10,000 / Tape & Reel
BC848CLT3G		SOT-23 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BC846ALT1 Series

ORDERING INFORMATION

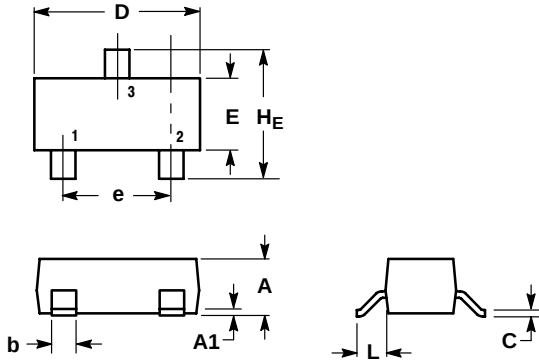
Device	Marking	Package	Shipping [†]
BC849BLT1	2B	SOT-23	3,000 / Tape & Reel
BC849BLT1G		SOT-23 (Pb-Free)	
BC849BLT3		SOT-23	10,000 / Tape & Reel
BC849BLT3G		SOT-23 (Pb-Free)	
BC849CLT1	2C	SOT-23	3,000 / Tape & Reel
BC849CLT1G		SOT-23 (Pb-Free)	
BC849CLT3		SOT-23	10,000 / Tape & Reel
BC849CLT3G		SOT-23 (Pb-Free)	
BC850BLT1	2F	SOT-23	3,000 / Tape & Reel
BC850BLT1G		SOT-23 (Pb-Free)	
BC850CLT1	2G	SOT-23	
BC850CLT1G		SOT-23 (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BC846ALT1 Series

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AL



NOTES:

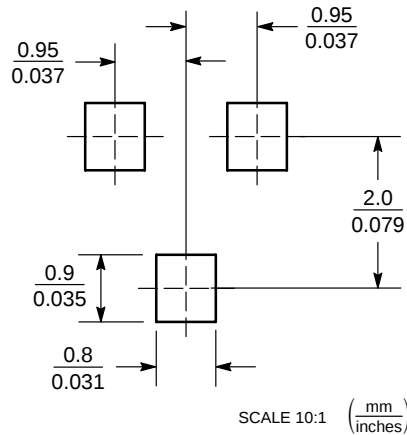
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.0350	0.0395	0.0440
A1	0.013	0.06	0.100	0.0005	0.0023	0.0040
b	0.037	0.44	0.50	0.0150	0.0175	0.0200
c	0.085	0.132	0.177	0.0034	0.0052	0.0070
D	2.80	2.90	3.04	0.1102	0.1140	0.1197
E	1.20	1.30	1.40	0.0472	0.0512	0.0551
e	1.78	1.90	2.04	0.0701	0.0750	0.0807
L	0.35	0.54	0.69	0.0140	0.0213	0.0285
He	2.10	2.40	2.64	0.0830	0.0940	0.1039

STYLE 6:

- PIN 1: BASE
2: EMITTER
3: COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

BC846ALT1 Series

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